AUTOMOTIVE GRADE

RoHS

COMPLIANT

HALOGEN

FREE



Vishay General Semiconductor

Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifiers

eSMP® Series



SMF (DO-219AB)

Cathode O Anode

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS			
I _{F(AV)}	3.0 A		
V_{RRM}	45 V		
I _{FSM}	50 A		
V_F at $I_F = 2 A (T_A = 125 °C)$	0.43 V		
T _J max.	150 °C		
Package	SMF (DO-219AB)		
Circuit configuration	Single		

FEATURES

- Trench MOS Schottky technology
- · Low profile package
- · Ideal for automated placement
- · Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- · Wave and reflow solderable
- AEC-Q101 qualified available
 Automotive ordering and a base D
 - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

MECHANICAL DATA

Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V3FL45	UNIT	
Device marking code		3LE		
Maximum repetitive peak reverse voltage		45	V	
Maximum average forward rectified current (fig.1)	I _{F(AV)} (1)	2.5	А	
Maximum average forward rectified current (fig.1)	I _{F(AV)} (2)	3.0		
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	50	А	
Operating junction temperature range	T _J ⁽³⁾	-40 to +150	°C	
Storage temperature range		-55 to +150		

Notes

- (1) Free air, mounted on FR4 PCB, 2 oz. standard footprint
- (2) Mounted on FR4 PCB, 2 oz.10 mm x 10 mm copper pad area
- $^{(3)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST C	ONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 1.5 A	T _A = 25 °C		0.44	-	V
	I _F = 3.0 A		V _E (1)	0.50	0.58	
	I _F = 1.5 A	- T _A = 125 °C	V F (*)	0.34	=	
	I _F = 3.0 A			0.43	0.51	
Reverse current	V _R = 45 V	T _A = 25 °C	I_ (2)	=	0.75	mA
	v _R = 45 v	T _A = 125 °C		4	15	IIIA
Typical junction capacitance	4.0 V, 1 MHz		CJ	370	=	pF

Notes

 $^{(1)}\,$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)				
PARAMETER SYMBOL V3FL45 UN				
Typical thormal registeries	R ₀ JA (1)(2)	125	°C/W	
Typical thermal resistance	R _{0JM} (3)	18	C/VV	

Notes

- $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$ Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance $R_{\theta JA}$ junction-to-ambient
- (3) Device mounted on 10 mm x 10 mm pad size area footprint; thermal resistance $R_{\theta JM}$ junction-to-mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V3FL45-M3/H	0.015	Н	3000	7" diameter plastic tape and reel
V3FL45-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V3FL45HM3/H (1)	0.015	Н	3000	7" diameter plastic tape and reel
V3FL45HM3/I (1)	0.015	I	10 000	13" diameter plastic tape and reel

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

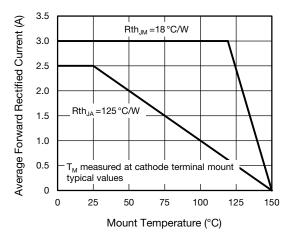


Fig. 1 - Maximum Forward Current Derating Curve

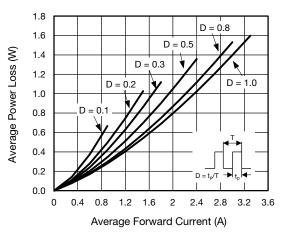


Fig. 2 - Average Power Loss Characteristics

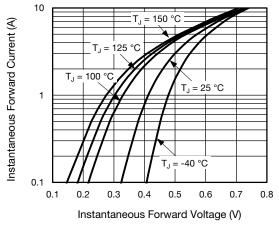


Fig. 3 - Typical Instantaneous Forward Characteristics

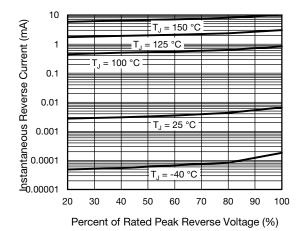


Fig. 4 - Typical Reverse Leakage Characteristics

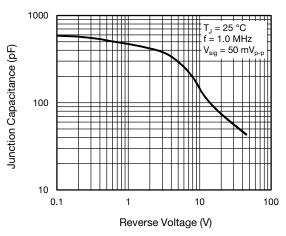


Fig. 5 - Typical Junction Capacitance

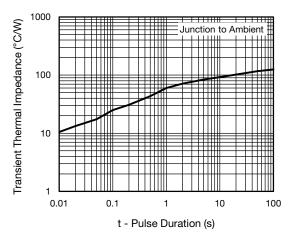
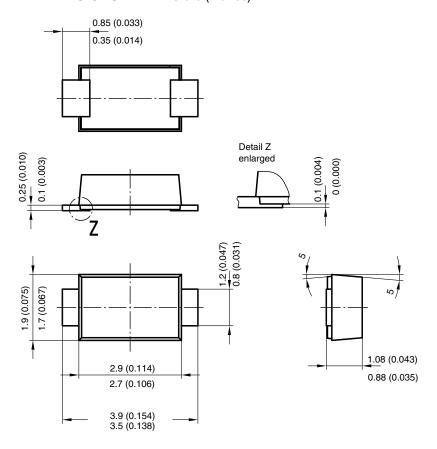


Fig. 6 - Typical Transient Thermal Impedance

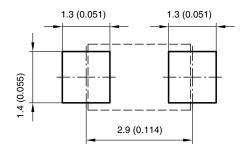


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PACKAGE OUTLINE DIMENSIONS in millimeters (inches)



Foot print recommendation:



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